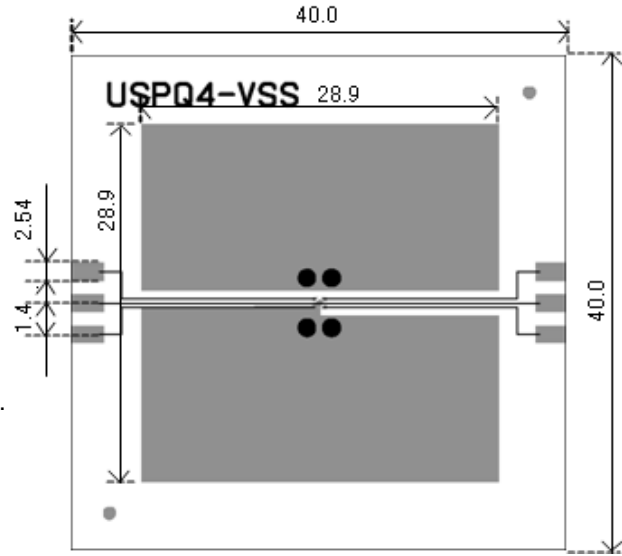


●USPQ-4B03 Power Dissipation

Power dissipation data for the USPQ-4B03 is shown in this page.
 The value of power dissipation varies with the mount board conditions.
 Please use this data as one of reference data taken in the described condition.

1. Measurement Condition (Reference data)

- Condition: Mount on a board
- Ambient: Natural convection
- Soldering: Lead (Pb) free
- Board Dimensions: 40 x 40 mm (1600mm²)
- Board Structure: 4 Copper Layers
 Each layer is connected to the package heat-sink and terminal pin No.1.
 Each layer has approximately 800mm² copper area.
- Material: Glass Epoxy (FR-4)
- Thickness: 1.6 mm
- Through-hole: 4 x 0.8 Diameter

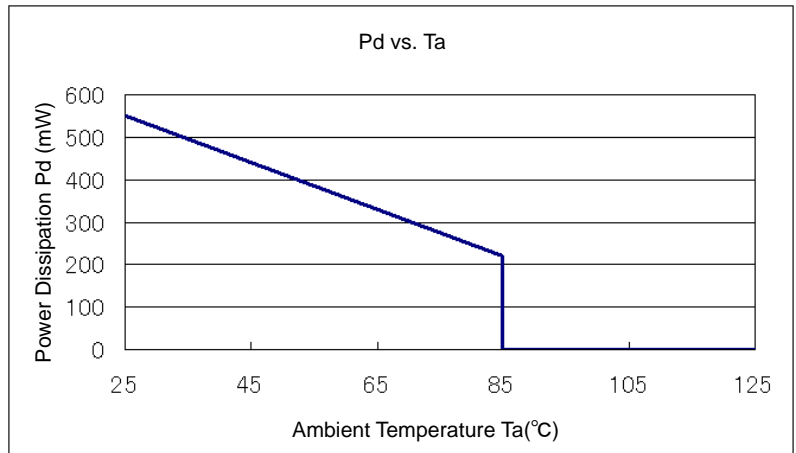


Evaluation Board (Unit: mm)

2. Power Dissipation vs. Ambient Temperature (85°C)

Board Mount (T_{jmax}=125°C)

| Ambient Temperature (°C) | Power Dissipation Pd (mW) | Thermal Resistance (°C/W) |
|--------------------------|---------------------------|---------------------------|
| 25 | 550 | 181.82 |
| 85 | 220 | |



3. Power Dissipation vs. Ambient Temperature (105°C)

Board Mount (T_{jmax}=125°C)

| Ambient Temperature (°C) | Power Dissipation Pd (mW) | Thermal Resistance (°C/W) |
|--------------------------|---------------------------|---------------------------|
| 25 | 550 | 181.82 |
| 85 | 110 | |

